MSKSEMI 美森科













ESD

TVS

TSS

MOV

GDT

PLED

MJD41CT4G(MS)

Product specification





TRANSISTOR (NPN)

FEATURES

- Designed for General Purpose Amplifier and Low Speed S witching Applications.
- Lead Formed for Surface Mount Applications in Plastic Sleeves
- Electrically Similar to Popular TIP41 and TIP42 Series
- Monolithic Construction With Built-in Base-Emitter Resistors

Reference News

PACKAGE OUTLINE		COMPLEMENTARY	Marking	
	1.BASE 2.COLLECTOR 3.EMITTER	COLLECTOR 2 1 BASE 3 EMITTER	MSKSEMI MJD41CT4G MS XXX	
			Notes :XXX represents the order cod	

MAXIMUM RATINGS (Ta=25 ℃ unless otherwise noted)

Symbol	Parameter	Value	Unit
Vсво	Collector-Base Voltage	100	V
V _{CEO}	Collector-EmitterVoltage	100	V
V _{EBO}	Emitter-Base Voltage	5	V
lc	Collector Current -Continuous	6	А
ICP*	Collector Current -Pluse	10	А
Pc	Collector Power Dissipation	1.25	W
T _{J,} T _{stg}	Operating Junction and Storage Temperature Range	-55-150	°C



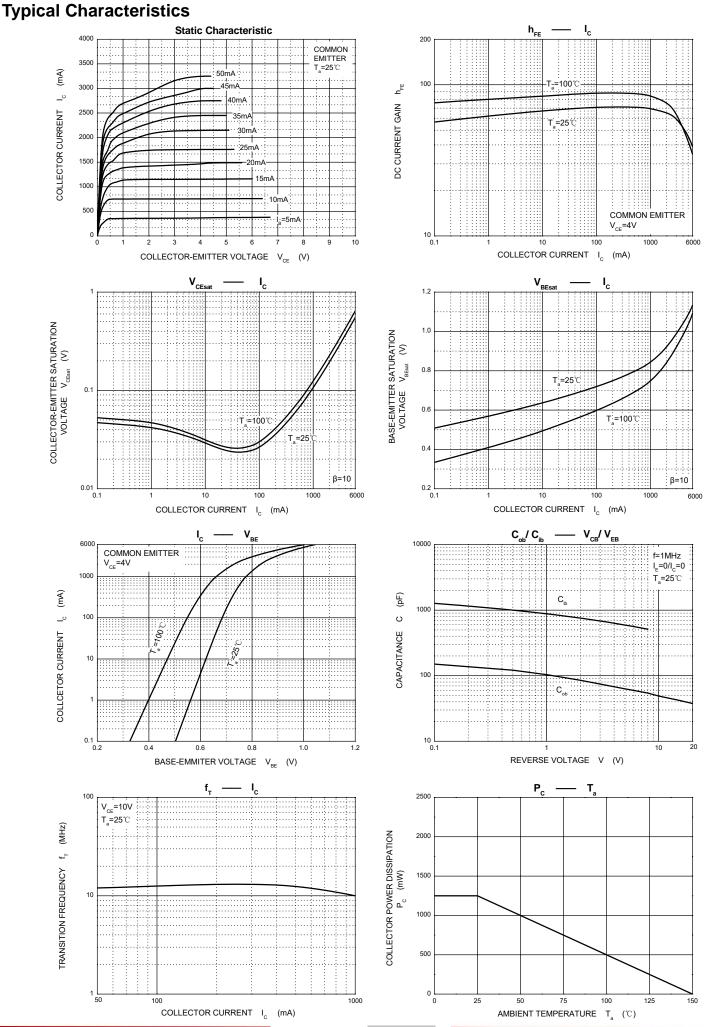
ELECTRICAL CHARACTERISTICS (T₄=25℃ unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Collector-base breakdown voltage	V(BR)CBO	lc=100μΑ,I _E =0	100			V
Collector-emitter breakdown voltage	V _{CEO(sus)}	Ic=30mA,I _B =0	100			V
Emitter-base breakdown voltage	V _{(BR)EBO}	l _E =100μA,I _C =0	5			V
Collector cut-off current	ICEO	V _{CB} =60V,I _E =0			50	μA
Emitter cut-off current	Іево	V _{EB} =5V I _C =0			0.5	mA
DC current acia	h _{FE(1)}	V _{CE} =4V I _C =0.3A	30			
DC current gain	h _{FE(2)}	V _{CE} =4V,I _C =3A	15		75	
Collector-emitter saturation voltage	V _{CE(sat)}	lc=6A,I _B =0.6A			1.5	V
Base-emitter voltage	V _{BE}	V _{CE} =4V,I _C =6A			2	V
Transition frequency	f⊤	V _{CE} =10V,I _C =500mA,f=1MHz	3			MHz

* Pulse Test: PW≤300µs, Duty Cycle≤2%



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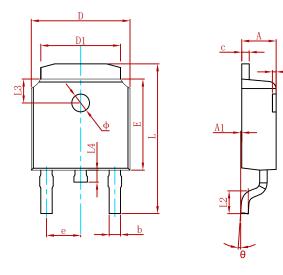
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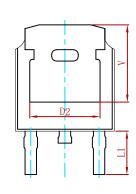
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PACKAGE MECHANICAL DATA

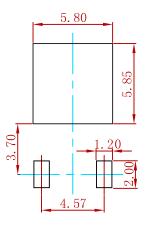




Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.635	0.770	0.025	0.030	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830	REF.	0.190 REF.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.712	10.312	0.382	0.406	
L1	2.900 REF.		0.114 REF.		
L2	1.400	1.700	0.055	0.067	
L3	1.600	REF.	0.063	REF.	
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.250 REF.		0.207	REF.	

h

Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.

2.General tolerance:±0.05mm.

3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
MJD41CT4G(MS)	TO-252	2500



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